

Title (en)
ALUMINUM ELECTROPLATING SOLUTION

Title (de)
ALUMINUMGALVANISIERUNGSLÖSUNG

Title (fr)
SOLUTION DE DÉPÔT ÉLECTROLYTIQUE D'ALUMINIUM

Publication
EP 2623643 A4 20150304 (EN)

Application
EP 11828690 A 20110901

Priority
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Abstract (en)
[origin: US2013168258A1] The purpose of the present invention is to provide an aluminum electroplating solution that allows aluminum electroplating to be conducted efficiently and in a short period of time, can increase the amount of electricity in the current of electroplating, and has high solubility in a nonaqueous solvent. This aluminum electroplating solution is characterized by comprising an aluminum metal salt, an ionic liquid obtained by an organic compound forming an ion pair with the aluminum metal salt, and an organic solvent having a dielectric constant of 8 or less. It is preferable for the volume percentage of the organic solvent in relation to the total volume of the ionic liquid and the organic solvent to be at least 30%, and for at least one of the following to be included as the organic solvent having a dielectric constant of 8 or less: hexane, toluene, diethyl ether, ethylacetate, cyclohexane, xylene, benzene, naphthalene, heptane, cyclopentyl methyl ether, and dioxane.

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C25D 3/44 (2006.01); **C25D 3/66** (2006.01)

CPC (source: EP US)
C25D 3/44 (2013.01 - EP US); **C25D 3/665** (2013.01 - EP US)

Citation (search report)
• [X] EP 0339536 A1 19891102 - NISSHIN STEEL CO LTD [JP], et al
• [A] EP 2130949 A1 20091209 - DIPSOL CHEM [JP], et al
• [A] EP 0398358 A2 19901122 - MITSUBISHI PETROCHEMICAL CO [JP], et al
• [A] JP H06293991 A 19941021 - SONY CORP

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